

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC100N10NSF G	**Issued**	24. February 2022
MA#	MA005700756		
Package	PG-TDSON-8-1	**Weight***	122.80 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.418	4.41	4.41	44118	44118
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		92	
	non noble metal	iron	7439-89-6	0.038	0.03		308	
	non noble metal	copper	7440-50-8	37.762	30.76	30.80	307510	307910
wire	non noble metal	copper	7440-50-8	0.028	0.02	0.02	229	229
encapsulation	organic material	carbon black	1333-86-4	0.078	0.06		634	
	plastics	epoxy resin	-	5.528	4.50		45016	
	inorganic material	silicondioxide	60676-86-0	33.323	27.14	31.70	271367	317017
leadfinish	non noble metal	tin	7440-31-5	1.452	1.18	1.18	11821	11821
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1348	1348
solder	non noble metal	tin	7440-31-5	0.081	0.07		660	
	noble metal	silver	7440-22-4	0.101	0.08		825	
	non noble metal	lead	7439-92-1	3.868	3.15	3.30	31499	32984
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	iron	7439-89-6	0.022	0.02		182	
	noble metal	silver	7440-22-4	1.289	1.05		10501	
	non noble metal	copper	7440-50-8	22.292	18.15	19.23	181531	192269
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	iron	7439-89-6	0.011	0.01		92	
	non noble metal	copper	7440-50-8	11.320	9.22	9.23	92184	92304
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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